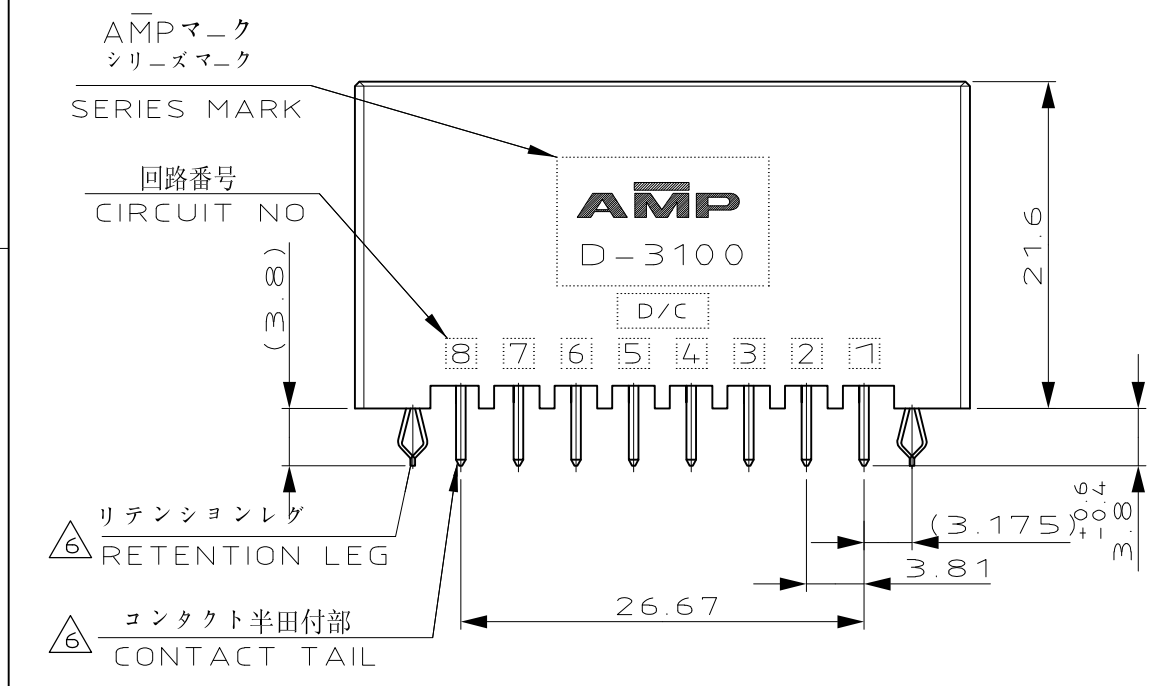
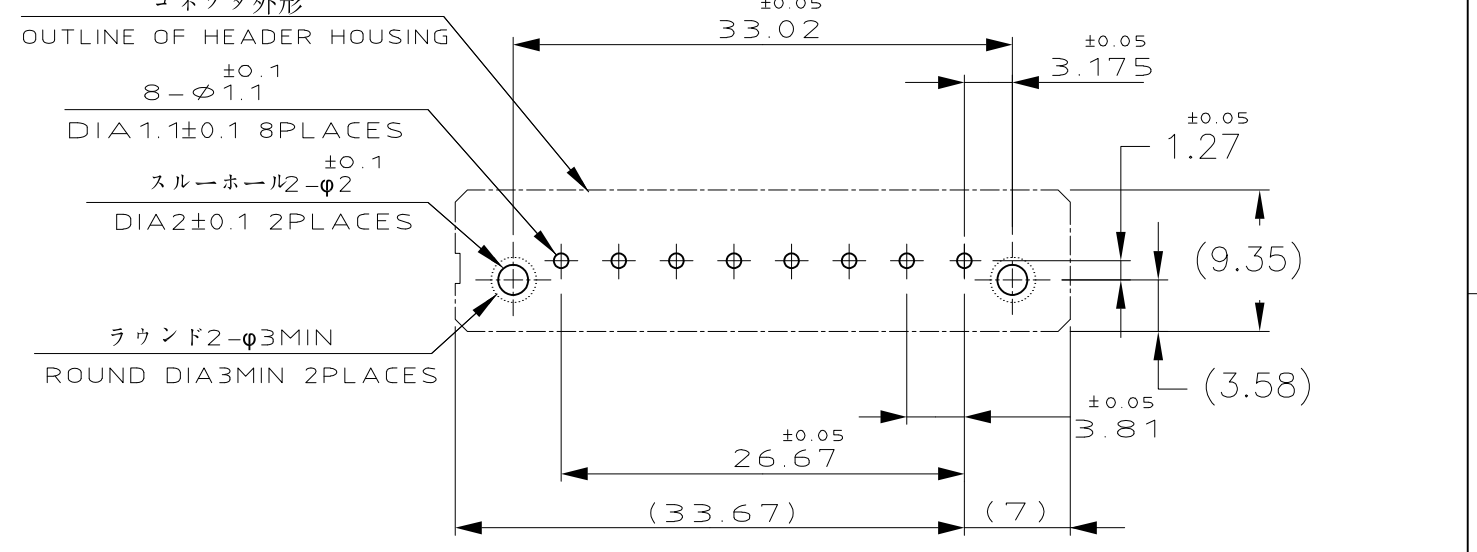
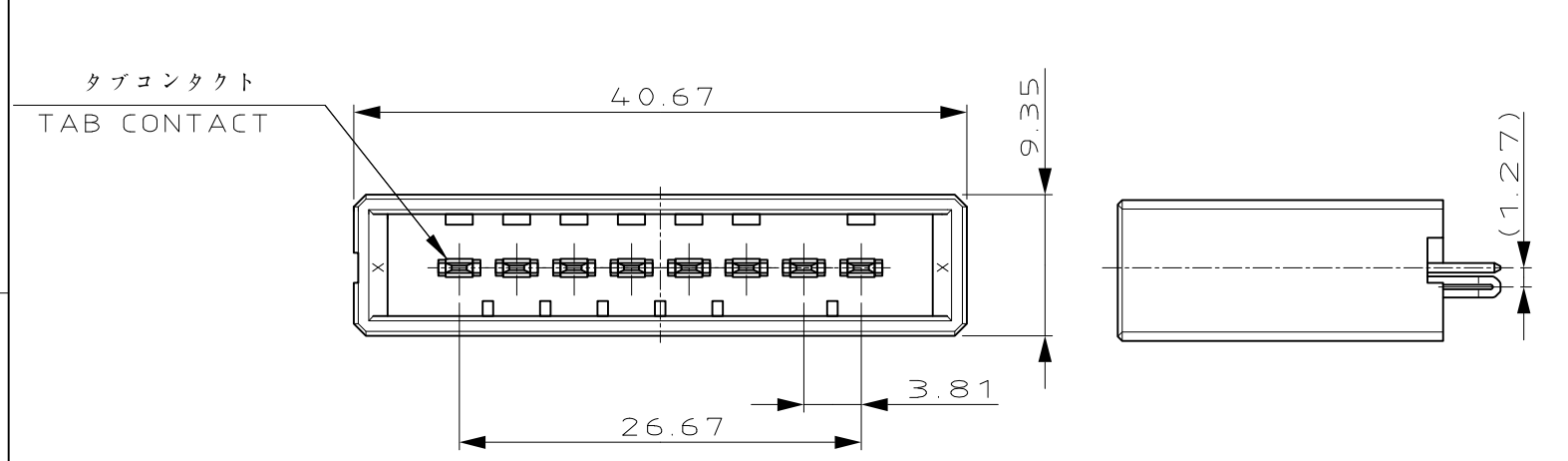


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LOC	DIST	REVISIONS					
J	-	P	LTR	DESCRIPTION	DATE	DWN	APVD
		F		REVISED	04JUL2012	H.M	N.Y



推奨基板取付け穴寸法  
 PC 基板厚: 1.6 ± 0.1  
 (非累積公差)  
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
 PC BOARD THICKNESS: 1.6 ± 0.1  
 (NOT ACCUMULATE TOLERANCE)  
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒  
 コンタクト: 銅合金  
 リテンションレグ: 銅合金
- めっき: コンタクト 全面 Ni 下地  
 接触部 0.38 μm MIN 金めっき
- めっき: コンタクト 全面 Ni 下地  
 接触部 0.76 μm MIN 金めっき
- めっき: コンタクト 全面 Ni 下地  
 接触部 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の土に半田めっき
- めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の土にスズめっき

△6	△4	1-178317-5
△6	△3	1-178317-3
△6	△2	1-178317-2
(FINISH)		製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN N.MATSUBARA 19APR1994	TE Connectivity	
		CHK S.MANABE 20APR1994		
DIMENSIONS: mm		APVD S.MANABE 20APR1994	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC	8 POS SINGLE ROW VERTICAL HDR ASSY FOR DYNAMIC D-3100	
0 PLC ± 1 PLC ± 2 PLC ±10° ±0.3 3 PLC ±10° 30° ±0.4 4 PLC ±30° 110° ±0.45 ANGLES ±3°		APPLICATION SPEC	SIZE CAGE CODE DRAWING NO RESTRICTED TO	
MATERIAL SEE NOTE		WEIGHT	A3 00779 C-178317	
FINISH SEE NOTE		CUSTOMER DRAWING		SCALE 2:1 SHEET 1 OF 1 REV F